

## **Invitation to JPCA Show 2019**

To Our Valued Customers:

We are pleased to inform you that we will be exhibiting at upcoming JPCA Show 2019 (PWB Tech 2019) at Tokyo Big Sight, Japan. It is our honor to invite you to our booth and share the specific details about our products and technologies.

Date: June 5 (Wed.) – June 7 (Fri.) 10:00 – 17:00 \* Until 16:00 on the last day Venue: Tokyo Big Sight Access: http://www.jpcashow.com/show2019/en/arrival/index.html

## [Exhibits]

$\Box$ Acid copper plating additives for via filling	$\Box$ Products for Fan-Out packaging process
application with fine pattern	– LtF Process –
$\Box$ Dry film resist stripper for fine pattern	□ Melplate UBM Process
application	
□Electroless copper seed layer etching	□Cleaner for DFR developing/stripping tank
solution for SAP	
□Acid cleaner for fine pattern application	□Multistage electrolytic sterilizer
$\Box$ Products for MSAP	

## [Exhibitor's (NPI) Presentation] \* Free admission

[Title]: Development Trend of Dry Film Resist Stripper

[Content]: Our action for development of DFR stripper and eco-oriented policy will be presented.
[Speaker]: Ms. Nana Hattori PWB Application Development, Technology Development Dept.
[Date]: June 6 (Thu.) 11: 30 - 12:00

[Venue]: <West Hall 2, Meeting Room 6> NPI Presentation Room B

\*Please come directly to the venue if you want to attend the presentation.

